10th International Conference on E-Learning in Industrial Electronics (ICELIE 2023)

Special Session on

“Education in Cross-Disciplinary Engineering”

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Call for Papers

Theme: As the technological landscape continues to evolve at a rapid pace, it has become increasingly crucial for engineers to possess a diverse skill set and a comprehensive understanding of multiple disciplines. In this context, the exploration of cross-disciplinary engineering education is becoming increasingly important for fostering innovation, enabling collaboration, and addressing
global challenges. The session will focus on how education in cross-disciplinary engineering fosters innovation, enables collaboration, and addresses complex global challenges. This special session aims at sharing insights, experiences, and best practices in cross-disciplinary engineering education of esteemed experts and professionals from various disciplines. They will discuss the benefits, challenges, and effective strategies for integrating different fields of study to create well-rounded engineers capable of tackling the complex problems of the modern world. This special session is sponsored by the technical committees belonging to the IEEE IES Cross-disciplinary Cluster.

Topics of interest include, but are not limited to:

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**Submissions Procedure:**

All the instructions for paper submission are included in the conference website: [http://www.icelie.org/](http://www.icelie.org/)

**Deadlines:**

- Full paper submission: Jun 30, 2023
- Paper acceptance notification: July 20, 2023
- Camera-ready paper submission: Aug. 25, 2023

**Sponsor:**

This SS is sponsored by the IEEE IES Technical Committee on Education in Engineering and Industrial Technologies, by the IEEE IES Technical Committee on Electronic Systems on Chip, by the IEEE IES Technical Committee on Human Factors, by the IEEE IES Technical Committee on Resilience and Security for Industrial Applications, by the IEEE IES Technical Committee on Standards, and by the IEEE IES Technical Committee on Technology Ethics and Society.